

October 2007

FAN5631 / FAN5632 Regulated Step-Down Charge Pump DC/DC Converter

Features

- 90% Peak Efficiency
- Low EMI
- Low Ripple
- Selectable Output Voltage:1.2V/1.5V for FAN5631
- Efficiency Optimizer Feature for FAN5632
- Input Voltage Range: 2.2V to 5.5V
- Output Current: Up to 250mA
- ±5% Output Voltage Accuracy
- 30µA Operating Current
- I_{CC}<1mA in Shutdown Mode</p>
- 1.5MHz Operating Frequency
- Shutdown Isolates Output from Input
- Soft-Start Limits Inrush Current
- Short-Circuit and Over-Temperature Protection
- Minimum External Component Count
- 10-Lead 3x3mm MLP Package

Applications

- Cell Phones
- Handheld Computers
- Portable Electronic Equipment
- Core Supply to Next-Generation Processors
- Low-Voltage DC Bus
- Digital Cameras
- DSP Supplies

Description

The FAN5631/FAN5632 is an advanced, thirdgeneration switched capacitor step-down DC/DC converter utilizing Fairchild's proprietary ScalarPump technology. This innovative architecture utilizes scalar switch re-configuration and fractional switching techniques to produce low output ripple, lower ESR spikes, and improve efficiency over a wide load range.

The FAN5631/FAN5632 produces a fixed regulated output voltage from an input voltage of 2.2V to 5V.

To maximize efficiency, the FAN5631/5632 achieves regulation by skipping pulses. Depending on load current, the size of the switches are scaled dynamically; consequently, current spikes and EMI are minimized. An internal soft-start circuitry prevents excessive current from the supply. The device is internally protected against short-circuit and over-temperature conditions.

The FAN5631 has a dual-output voltage feature. When V_{SEL} is high, V_{OUT} is 1.5V; and when V_{SEL} is low, V_{OUT} is 1.2V.

The FAN5632 has an efficiency optimizer feature that, when enabled, changes the switch mode configuration from 2:1 to 1:1 at the lower threshold of $V_{\rm IN}$. The efficiency is maintained at its peak level over a wider range of input voltages. In addition, $V_{\rm OUT}$ varies from 1.2V to 1.5V as a result of this efficiency optimization. If the efficiency optimizer is not enabled, $V_{\rm OUT}$ is regulated to 1.5V.

Both the FAN5631 and FAN5632 are available in a 10-lead 3x3mm MLP package.

Ordering Information

Part Number	Part Number Package	
FAN5631MPX	10-Lead 3x3mm Molded Leadless Package (MLP)	Tape and Reel
FAN5632MPX	10-Lead 3x3mm Molded Leadless Package (MLP)	Tape and Reel

All packages are lead free per JEDEC: J-STD-020B standard.

Typical Application

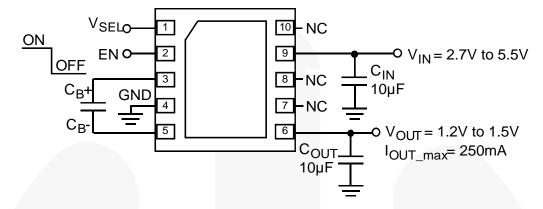
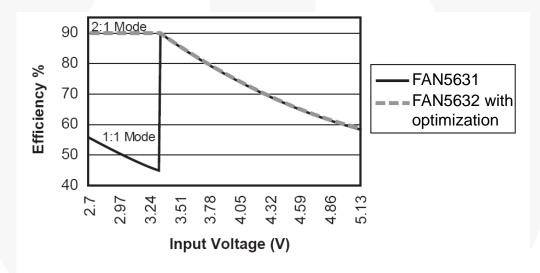


Figure 1. Typical Application



Average Efficiency (over V_{IN} =2.7V to 5V) = 66%, with optimization = 77% Average Efficiency (over V_{IN} =2.7V to 4.2V) = 67%, with optimization = 84%

Figure 2. Typical Efficiency Graph

Pin Configuration

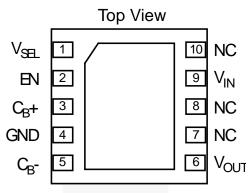


Figure 3. Pin Assignments

Pin Definitions

Pin#	Name	Description		
		Output Voltage Select Logic Input Pin. The V _{SEL} pin cannot be left floating and must be connected to either a logic high or logic low level.		
1	V_{SEL}	FAN5631 : If a logic low is applied to the V_{SEL} pin, V_{OUT} is 1.2V; if a logic high is applied, V_{OUT} is 1.5V.		
		FAN5632 : If a logic low is applied to the V _{SEL} pin, the efficiency optimization mode is enabled and the output voltage accuracy is relaxed to meet optimum efficiency. If a logic high is applied, the device operates like a typical charge pump converter.		
2	EN	Enable Input Pin. If a logic high is applied to the EN pin, the device is enabled. If a logic low is applied, the device is disabled and the supply current is reduced to less than 1µA. The EN pin cannot be left floating and must be connected to a logic high or logic low level.		
3	C _B +	Bucket Capacitor Positive Pin.		
4	GND	Ground Pin . This pin is connected to the internal MOSFET switches. This pin must be externally connected to GND.		
5	C _B -	Bucket Capacitor Negative Pin.		
6	V _{OUT}	Output Voltage Pin.		
7	NC	Not Connected. This pin is not internally connected.		
8	NC	Not Connected. This pin is not internally connected.		
9	V _{IN}	Supply Voltage Input.		
10	NC	Not Connected. This pin is not internally connected.		

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
V _{CC}	V _{IN} to GND	-0.3	6.0	V	
V CC	All other pins to GND	-0.3	V _{IN} + 0.3		
I _{LOAD}	Load Current		0.5	Α	
$\Theta_{\sf JC}$	Thermal Resistance Junction-to-Tab ⁽¹⁾		8	°C/W	
T∟	Lead Temperature, Soldering 10 Seconds		+260	°C	
T_J	Junction Temperature	-40	+150	°C	
T _{STG}	Storage Temperature	-65	+150	°C	
ESD ⁽²⁾	Human Body Model, JESD22-A114	2.5		kV	
ESD	Charged Device Model, JESD22-C101	0.2		KV	

Notes

- Junction-to-ambient thermal resistance, θ_{JA}, is a strong function of PCB material, board thickness, thickness and number of copper planes, number of via used, diameter of via used, available copper surface, and attached heat sink characteristics. The estimated value for zero air flow at 0.5W is 60°C/W.
- 2. Using Mil Std. 883E, method 3015.7 (Human Body Model) and EIA/JESD22C101-A (Charged Device Model).

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Тур.	Max.	Unit
V_{CC}	Supply Voltage Range	2.2		5.5	V
l _{OUT}	Output Current (V _{IN} > 2.V)			250	mA
T _A Operating Ambient Temperature Range		-40	+25	+85	°C

Electrical Characteristic

 $V_{IN}=2.2V$ to 5.5V, $I_{OUT}=1$ mA, $C_{IN}=10\mu F$, $C_{OUT}=10\mu F$, $C_B=1\mu F$, $T_A=-40^{\circ}C$ to +85°C, unless otherwise noted. Typical values are at $T_A=25^{\circ}C$.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units	
V_{UVLO}	Input Under-voltage Lockout			2		V	
	No-load Supply Current	No Switching			60	μΑ	
		FAN5631, SEL to High		1.5			
		FAN5631, SEL to Low		1.2			
V _{OUT}	Output Voltage	FAN5632, SEL to High		1.5		V	
		FAN5632, SEL to Low		Variable between 1.5 and 1.2			
	Output Voltage Accuracy	$1\text{mA} \le I_{\text{OUT}} \le 150\text{mA}, V_{\text{IN}}=2.7\text{V to}$ 5.5V	-5		+5	%	
R _{LOAD}	Load Regulation	$0mA \le I_{OUT} \le 150mA$, V_{IN} =3.6V		0.25		mV/mA	
R _{LINE}	Line Regulation	I _{OUT} =0.1mA		0.2	4.0	mV/V	
I _{SD}	Shutdown Supply Current	V _{EN} =0V		0.1	1.0	μΑ	
Isc	Output Short-circuit Current (3)	V _{OUT} ≤ 150mA		25		mA	
	Peak Efficiency			90		%	
	V _{IN} at Configuration Change	V _{IN} Decreasing		2.22xV _{OUT}		V	
Fosc	Oscillator Frequency			1.5		MHz	
TSD	Thermal Shutdown Threshold			150		°C	
TSD _{HYS}	Thermal Shutdown Threshold Hysteresis			15		°C	
V _{IH}	Enable Logic Input High Voltage		1.3			V	
V_{IL}	Enable Logic Input Low Voltage				0.4	V	
I _{EN}	Enable Logic Input Current		-1		1	μΑ	
V _{IH}	V _{SEL} Logic Input High Voltage		1.3			V	
VIL	V _{SEL} Logic Input Low Voltage				0.4	V	
I _{IN}	V _{SEL} Logic Input Current		-1		1	μΑ	
ton	V _{OUT} Turn-On Time			1.6	У	ms	

Note:

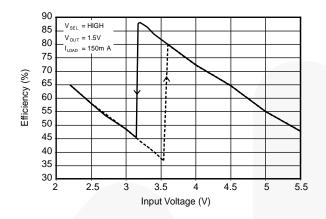
3. The short-circuit protection is designed to protect against pre-existing short-circuit conditions, such as assembly shorts, that exist prior to device power-up. The short-circuit current limit is 25mA_{Average}. Short-circuit currents in normal operation are inherently limited by the on resistance of the internal FET. Since this resistance is in the range of 1Ω, in some cases, thermal shutdown may occur. Immediately following the first thermal shutdown event, the short-circuit condition is treated as pre-existing and the load current reduces to 25mA_{Average}.

Typical Performance Characteristics

 $T_A = 25$ °C, $V_{OUT} = 1.5$ V, $V_{IN} = 3.6$ V, $C_{IN} = 10\mu F$, $C_{OUT} = 10\mu F$, $C_B = 1\mu F$, unless otherwise noted.

85

VIN = 3.3V

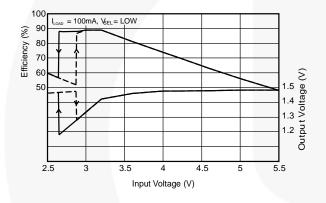


80 8 75 Efficiency 70 VIN = 4.2V 65 60 Power 55 VIN = 2.7V50 45 40 10 100 Load Current (mA)

VSEL= HIGH

Figure 4. Efficiency vs. Input Voltage

Figure 5. Efficiency vs. Load Current



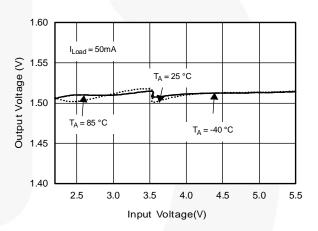
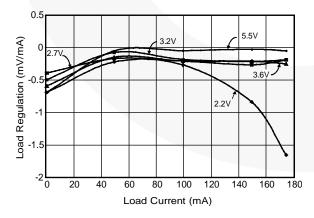


Figure 6. FAN5632 Efficiency Optimizer Efficiency and Output Voltage vs. Input Voltage

Figure 7. Line Regulation



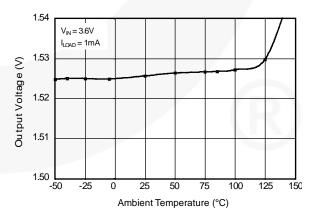


Figure 8. Load Regulation

Figure 9. Thermal Regulation

Typical Performance Characteristics (Continued)

 $T_A = 25^{\circ}C$, $V_{OUT} = 1.5V$, $V_{IN} = 3.6V$, $C_{IN} = 10\mu F$, $C_{OUT} = 10\mu F$, $C_B = 1\mu F$, unless otherwise noted.

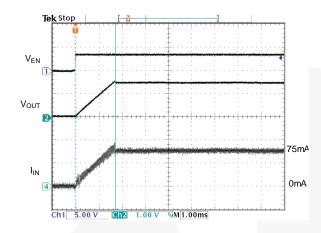


Figure 10. Start-Up

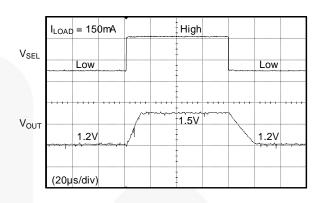


Figure 11. Dynamic V_{OUT} Change (FAN5631)

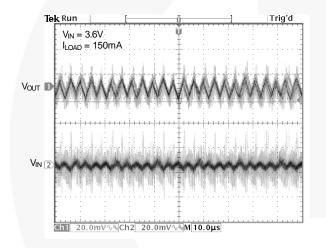


Figure 12. Voltage Ripple

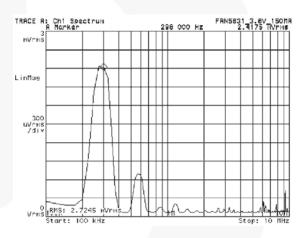


Figure 13. Output Voltage Ripple Spectrum

Block Diagram

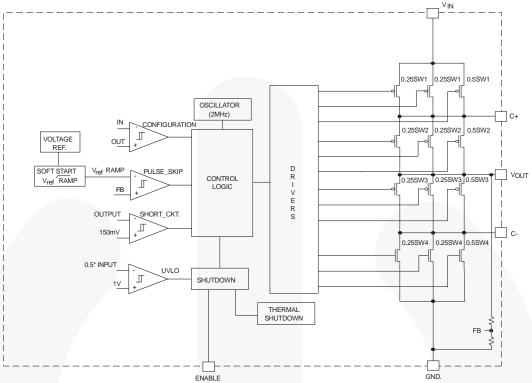


Figure 14. Block Diagram

Detailed Description

The FAN5631 / FAN5632 switched capacitor DC/DC converter automatically configures switches to achieve high efficiency and provides a regulated output voltage by means of pulse skipping, pulse frequency modulation (PFM). An internal soft-start circuit prevents excessive inrush current from the supply. Each switch is split into three segments. Based on the values of V_{IN} , V_{OUT} , and I_{OUT} ; an internal circuit determines the number of segments used to reduce current spikes.

Step-Down Charge Pump Operation

When $V_{\text{IN}} \geq 2 \times V_{\text{OUT}}/9$, the 2:1 configuration shown in Figure 15 is enabled. The factor 0.9 is used instead of 1 to account for the effect of resistive losses across the switches and to accommodate hysteresis in the voltage detector comparator. Two-phase, non-overlapping clock signals are generated to drive four switches. When switches 1 and 3 are on, switches 2 and 4 are off and C_B is charged. When switches 2 and 4 are on, 1 and 3 are off and charge is transferred from C_B to C_{OUT} .

When $V_{\text{IN}} \geq 2 \times V_{\text{OUT}}/9$, the 1:1 configuration shown in Figure 16 is enabled. In the 1:1 configuration, switch 3 is always off and the switch 4 is always on. At 1.6V output setting, the configuration changes from 2:1 to 1:1 at $V_{\text{IN}}{=}3.56V$. At 1.3V output setting, the change occurs at $V_{\text{IN}}{=}3.06V$.

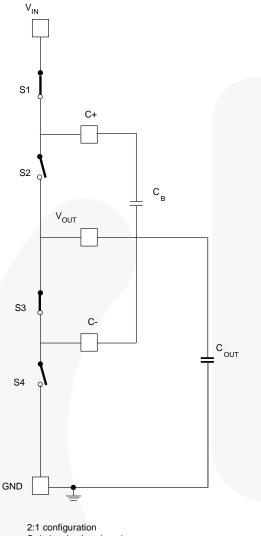
Pulse-skipping PFM and Fractional Switch Operation

When the regulated output voltage reaches its upper limit, the switches are turned off and the output voltage reaches its lower limit. In a step-down 2:1 mode of operation, with 1.6V output as an example; when the output reaches about 1.62V (upper limit), the control logic turns off all switches: switching stops completely. This is pulse-skipping mode. Since the supply is isolated from the output, the output voltage drops. Once the output is dropped to about 1.58V (lower limit), the device returns to regular switching mode with one quarter of each switch turning on first. Another quarter of each switch is turned on if Vout cannot reach regulation by the third charge cycle. Full switch operation occurs only during star-up or under heavyload condition, when half switch operation cannot achieve regulation within seven charge cycles.

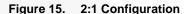
Soft-Start

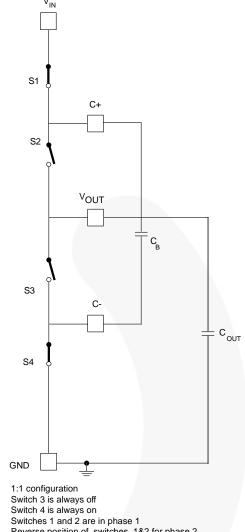
The soft-start feature limits inrush current when the device is initially powered up and enabled. The reference voltage is used to control the rate of the output voltage ramp-up to its final value. Typical start-up time is 1ms. Since the rate of the output voltage ramp-up is controlled by an internally generated slow ramp, pulse-skipping occurs and inrush current is automatically limited.

Switch Configuration



Switches in charging phase Reverse all switches for pumping phase





Reverse position of switches 1&2 for phase 2

Figure 16. 1:1 Configuration

Shutdown, UVLO, Short-Circuit, **Current-Limit and Thermal Shutdown**

The device has an active-low shutdown pin to decrease supply current to less than $1\mu A$. In shutdown mode, the supply is disconnected from the output. UVLO triggers when supply voltage drops below 2V. When the output voltage is lower than 150mV, a short-circuit protection is triggered. In this mode, 15 out of 16 pulses during the switching are skipped and the supply current is limited. Thermal shutdown triggers at 150°C.

Efficiency Optimizer (FAN5632)

In the FAN5632, V_{SEL} can be tied to ground to enable the efficiency optimizer feature. To achieve an optimized efficiency, the switch mode configuration transition point is shifted from a 2:1 to a 1:1 mode until the output voltage falls to 20% of its nominal value. For example, when the nominal output voltage is 1.5V, the output voltage is allowed to drop to 1.2V. This maintains a peak efficiency of 85% for the input voltage range of 2.9V to 3.5V. For normal operation, tie V_{SEL} high.

Applications Information

The FAN5631/FAN5632 requires one ceramic bucket capacitor in the $0.1\mu F$ to $1\mu F$ range, one $10\mu F$ output bypass capacitor, and one $10\mu F$ input bypass capacitor. To obtain optimum output ripple and noise performance, low-ESR (<0.05 Ω) ceramic input and output bypass capacitors are recommended. X5R- and X7R-rated capacitors provide adequate performance over the -40°C to 85°C temperature range.

The bucket capacitor's value is dependent on load current requirements. A $1\mu F$ bucket capacitor works well in all applications at all load currents, while a $0.1\mu F$ capacitor supports most applications under 100mA of load current. The choice of bucket capacitor values should be verified in the actual application at the lowest input voltage and highest load current. A 30% margin of safety is recommended to account for the tolerance of the bucket capacitor and the variations in the onresistance of the internal switches.

One of the key benefits of the ScalarPump architecture is that the dynamically scaled on resistance of the switches effectively reduces the peak current in the bucket capacitor and therefore input and output ripple currents are also reduced. Nevertheless, due to the ESR of the input and output bypass capacitors, these current spikes generate voltage spikes at the input and output pins. These ESR spikes can be filtered because their frequencies lie at up to 12 times the clock frequencies. In applications where conductive and radiated EMI/RFI interference must be low as possible, consider additional input and output filtering.

Layout Considerations

While evaluating any switched capacitor DC-DC converter, be careful to keep the power supply source impedance low; use of long wires causing high lead inductances and resistive losses should be avoided. A carefully laid-out ground plane is essential because current spikes are generated as the bucket capacitor is charged and discharged. The input and output bypass capacitors should be placed as close to the device pins as possible.

0.25

Physical Dimensions 10 3.0 Α ○ 0.15 C 2.25 2.20 2X В 2.00 0.55 0.78 2.33 25 2.00 3.0 0.23 0.15 C 0.02 2X **TOP VIEW** 0.8 MAX-RECOMMENDED LAND PATTERN 0.10 C -(0.20)○ 0.08 C 0.05_ C SIDE VIEW SEATING **PLANE** (3.00±0.10) 2.25±0.05 -PIN #1 IDENT (0.38)5 (3.00±0.10) 1.55±0.05 0.40±0.05 0.30 0.5

BOTTOM VIEW

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, **VARIATION WEED-5**
- B. DIMENSIONSARE IN MILLIMETERS.
- C. DIMENSIONSAND TOLERANCESPER ASME Y14.5M, 1994
- LAND PATTERN DIMENSIONSARE NOMINAL **REFERENCE VALUES ONLY**

MLP10BrevA

Figure 17. 10-lead, Molded Leadless Package (MLP)

0.10 M C A B 0.05 M C





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